



400G (8x56G) QSFP-DD PAM4 to 400G (8x56G) QSFP-DD PAM4

Plug & Play Active Electrical Cable for In-Rack Ethernet Applications in Distributed, Disaggregated Chassis (DDC)

Description

Credo's HiWire[™] Low Power CLOS Active Electrical Cable (LP CLOS AEC) is a thin, low power 400G AEC specifically designed for in-rack applications replacing backplanes in Distributed, Disaggregated Chassis (DDC) implementations. Plug & Play LP CLOS AECs consume up to 75% less power and take 75% less volume than DACs, enabling interconnect densities of up to 500 cables per rack.

Credo's **CAC4XX321D1D-XX-HW HiWire LP CLOS AEC** is designed for telecom and data center use. It can sustain 8 lanes of 56G-PAM4 signal in each direction, providing bi-directional 400Gbps traffic per cable. The use and replacement of this AEC is simple and straightforward as it adopts standard QSFP-DD type 2 form factor and complies to MSA specifications.



1:1 Direct LP CLOS AEC

Product Selections

| Part Number | Length | AWG | Weight |
|--------------------|--------------|-----|----------|
| CAC4XX321D1D-C0-HW | 0.5 - 2.5m* | 32 | CMIS 3.0 |
| CAC4xx321D1D-D0-HW | 0.5 - 2.5m* | 32 | CMIS 4.0 |
| CAC4xx321D1D-A0-HW | 1.75 - 2.5m* | 32 | 788g |

*Length available in 0.25m increments

Mechanicals

| Parameter | Cable Type | Typical | Length |
|-----------|------------|---------|------------|
| Diameter | 16P 32AWG | 6.8mm | 0.5 - 3.0m |

Supported Standards

The following are the key features of the HiWire cable:

- Common Management Interface Specification (CMIS) v3.0 and v4.0
- QSFP-DD MSA v3.0

Product Features

The following are the key features of the HiWire LP CLOS AEC:

- Recognizable, purple PVC jacket
- 400G to 400G data rate
- Built-in diagnostic features
- CMIS compliant
- Single 3.3V power supply
- Typ. 4.5W power dissipation each end
- BER < 10^{^-15} (post FEC)
- Hot pluggable
- RoHS2 compliant
- I²C management interface
- Operating case temperature range: 0° to +70°C

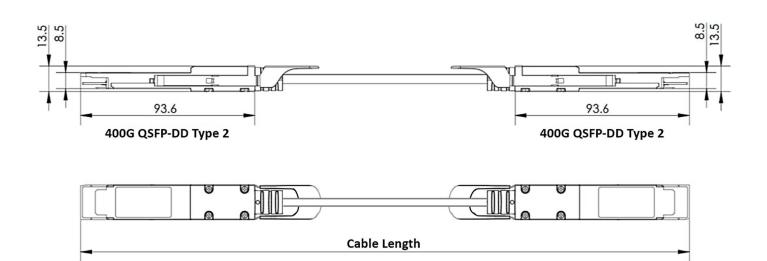


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General Product Characteristics

| Parameter | Value | | |
|----------------------------------|---|--|--|
| Module Form Factor | QSFP-DD type 2 | | |
| Number of Data Lanes | 8 TX and 8 RX per module (PAM4) | | |
| Maximum Aggregate Data Rate | 400Gbps | | |
| Nominal Data Rate per Lane | 53.125Gbps (PAM4) | | |
| Electrical Interface and Pin-out | 76-pin edge connector | | |
| Pin Description | Per QSFP-DD Hardware Specification | | |
| Management Interface | I ² C, serial, timing per Common Management Interface Specification for 8X/16X Pluggable Transceivers (QSFP-DD) | | |
| Length of Copper AEC | 0.5m - 2.5m in 0.25m increments | | |
| BER (Pre-FEC)* | Typ. <10 ⁻⁸ * Tested with QPRBS31 pattern | | |
| BER (Post-FEC)* | <10 ⁻¹⁵ * Tested with QPRBS31 pattern | | |



For more information please visit www.credosemi.com/hiwire-aec or email hiwire@credosemi.com

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